

ABSTRACT

**CHEMICALLY-AMPLIFIED POSITIVE-TYPE PHOTSENSITIVE RESIN
COMPOSITION, METHOD FOR MANUFACTURING COMPOSITE SUBSTRATE
WITH CASTING MOLD, AND METHOD FOR MANUFACTURING
ELECTROPLATED MOLDED ARTICLE**

5 A chemically-amplified positive-type photosensitive resin composition includes an acid-dissociable resin (A), an alkali-soluble resin (B), a photoacid generator (C), and a solvent component (D). The solvent component (D) includes a solvent (D1) that has a boiling point ranging from 150°C to 190°C. A dry film
10 formed from the chemically-amplified positive-type photosensitive resin composition is subjected to Fourier transform infrared spectroscopy (FTIR) measurement. A ratio of a signal intensity of a hydroxy (–OH) group (I_{OH}) to a signal intensity of a carbonyl (C=O) group (I_{CO}) of the dry film ranging from 0.12 to 0.9. A method for manufacturing a composite substrate with casting mold, and a method
15 for manufacturing an electroplated molded article are also provided.

FIG. 1 is suggested for publication.